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### **NEXX Systems Names Daniel O'Connell As Director of North America Sales**

**Billerica, MA – March 2, 2009**– NEXX Systems, a leading provider of processing equipment for advanced wafer-level packaging applications, today announced that it has named Daniel O'Connell as Director of North America Sales. Mr. O'Connell joined NEXX in May 2008 and has 12 years of semiconductor sales and account management experience with Novellus, Ebara, and BOC Gases (Linde). He will work to strengthen NEXX's position with existing customers and successfully exploit new opportunities in North America. Announced simultaneously were the promotions of Mark Welsh and David Volfson, both as Senior Product Managers. Messrs. Welsh and Volfson have, respectively, more than 25 and 20 years in the semiconductor capital equipment business.

Stated John Bowers, Vice President of Sales and Business Development at NEXX Systems, "We are delighted to recognize the contributions of Dan, Mark, and David to the NEXX team. Individually, they bring a wealth of experience in semiconductor business and, as a team, bring insights, customer knowledge, and energy that will serve our customers effectively and grow NEXX business."

**About NEXX:** NEXX Systems brings exceptional technical expertise to the flip chip and advanced packaging markets. Our product lines provide the most efficient, yet affordable, systems of their kind: Stratus for high throughput electro-deposition of metals, and Apollo and Nimbus for multi-layer sputter deposition of metals. Additional information can be found at: [www.nexxsystems.com](http://www.nexxsystems.com).